MA3D761 (MA7D61)

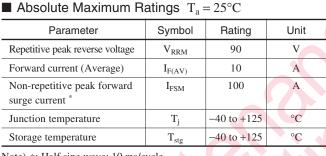
Silicon epitaxial planar type (cathode common)

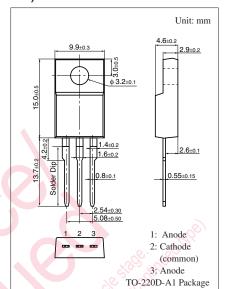
For switching mode power supply

■ Features

- Low forward voltage V_F
- High dielectric breakdown voltage: > 5 kV
- Easy-to-mount, due to its V cut lead end

Parameter	Symbol	Rating	Unit	
Repetitive peak reverse voltage	V _{RRM}	90	V	
Forward current (Average)	I _{F(AV)}	10	A	
Non-repetitive peak forward surge current *	I_{FSM}	100	A	
Junction temperature	T _j	-40 to +125	°C	
Storage temperature	T_{stg}	-40 to +125	°C	





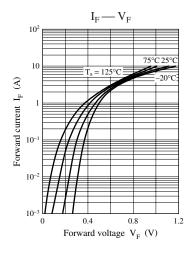
Note) *: Half sine wave; 10 ms/cycle

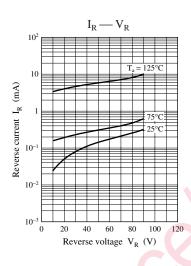
■ Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

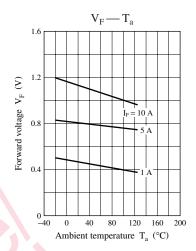
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	V_{F}	$I_F = 5 \text{ A}, T_C = 25^{\circ}\text{C}$			0.85	V
Reverse current	I_R	$V_R = 90 \text{ V}, T_C = 25^{\circ}\text{C}$			3	mA
Thermal resistance (j-c)	R _{th(j-c)}	The state of the s			3.0	°C/W

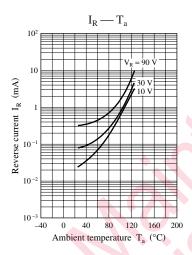
- Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.
 - 2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
 - 3. Absolute frequency of input and output is 100 MHz.

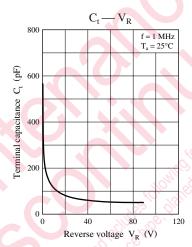
Note) The part number in the parenthesis shows conventional part number.

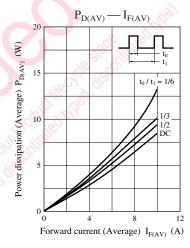


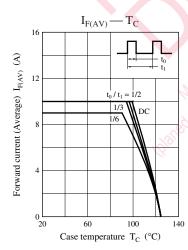












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